

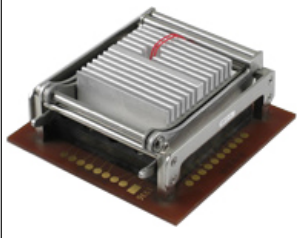







Test & Burn-In Socket Clamshell type & Open Top type

LGA Sockets (3)


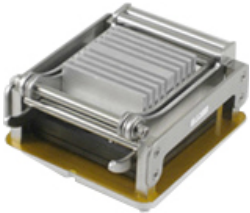
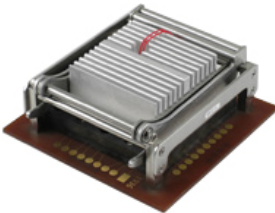
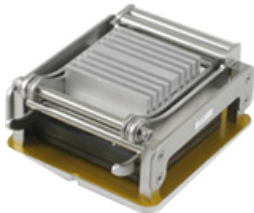
	LGA ES micro M-pin probe socket, Clamshell	LGA ESJ M-pin probe socket, Clamshell	LGA ES1 M-pin probe socket, Clamshell	LGA ES2 M-pin probe socket, Clamshell
	基板押し当てタイプ Mounting to PCB : Compression mount			
				
Features	<ul style="list-style-type: none"> ・経済性に優れています ・多くの標準品が揃っています ・Cost competitive ・There are many standard products. 	<ul style="list-style-type: none"> ・優れたクランプ機構付 ・再利用可能な設計 ・ヒートシンク交換可能 ・メンテナンスと修理が簡単 		
Mechanical Spec	Pitch:0.4mm-0.65mm Package Size:□9mm to □23mm Pin Count:1000 pin max Contact Force:14.5gf to 30.9gf Temperature:-55℃ to +150℃ Socket Dimensions:W-43.29mm L-56.46mm H-28.86mm	Pitch:1.0mm Package Size:□15mm to □31mm Pin Count:900 pin max Contact Force:34.9gf Temperature:150℃+ Mechanical Life:50,000+ Socket Dimensions:W-65.22mm L-86.81mm H-35.63mm	Pitch:1.0mm Package Size:□27mm to □45mm Pin Count:1,936 pin max Contact Force:34.9gf Temperature:150℃+ Mechanical Life:50,000+ Socket Dimensions:W-80.22mm L-101.81mm H-36.67mm	Pitch:1.0mm Package Size:□45mm to □60mm Pin Count:3,481 pin max Contact Force:34.9gf Temperature:150℃+ Mechanical Life:50,000+ Socket Dimensions:W-95.22mm L-116.81mm H-35.82mm
Electrical Spec	Contact Resistance:<35 mΩ Current Rating:>1.0 amp Bandwidth @-1dB:10 to 15.7 GHz	Contact Resistance:<16 mΩ Self Inductance:0.93 nH Bandwidth @-1dB:23.2 GHz		

BGA Sockets (1)

	BGA M-pin probe socket, Open top (RA series)	BGA M-pin probe socket, Clamshell (C series)	BGA M-pin probe socket, Clamshell (D series)	BGA M-pin probe socket, Clamshell (M series)
	基板押し当てタイプ Mounting to PCB : Compression mount			
				
Features	<ul style="list-style-type: none"> ・経済性に優れています ・多くの標準品が揃っています 			
Mechanical Spec	Pitch:0.4mm-0.8mm Package Size:□6mm to □9mm Pin Count:100 pin max Contact Force:14.5gf to 30.9gf Temperature:-55℃ to +180℃ Socket Dimensions:W-38.00mm L-34.00mm H-19.58mm	Pitch:0.35mm-0.8mm Package Size:□2mm to □9mm Pin Count:150 pin max Contact Force:14.5gf to 30gf Temperature:-55℃ to +180℃ Mechanical Life:50,000 cycles Socket Dimensions:W-25.00mm L-25.00mm H-14.24mm	Pitch:0.4mm-0.8mm Package Size:□9mm to □20mm Pin Count:300 pin max Contact Force:14.5gf to 30.9gf Temperature:-55℃ to +180℃ Socket Dimensions:W-37.34mm L-54.84mm H-22.00mm	Pitch:0.5mm-0.65mm Package Size:□12mm max Pin Count:576 pin max Contact Force:14.5gf Temperature:-55℃ to +150℃ Socket Dimensions:W-30.00mm L-30.00mm H-15.91mm
Electrical Spec	Contact Resistance:<30 mΩ Current Rating:>1.0 amp Bandwidth @-1dB:10 to 15.7GHz	Contact Resistance:<35 mΩ Current Rating:>1.0 amp Bandwidth @-1dB:>15.7GHz	Contact Resistance:<35 mΩ Current Rating:>1.0 amp Bandwidth @-1dB:10 to 15.7GHz	Contact Resistance:<35 mΩ Current Rating:>1.0 amp Bandwidth @-1dB:>15.7GHz



Test & Burn-In Socket Clamshell type

BGA Sockets (2)

	BGA ES micro M-pin probe socket, Clamshell	BGA ESJ M-pin probe socket, Clamshell	BGA ES1 M-pin probe socket, Clamshell	BGA ES2 M-pin probe socket, Clamshell
	基板押し当てタイプ Mounting to PCB : Compression mount			
				
Features	<ul style="list-style-type: none"> ・経済性に優れています ・多くの標準品が揃っています ・Cost competitive ・There are many standard products. 	<ul style="list-style-type: none"> ・優れたクランプ機構付 Excellent clamping mechanism ・再利用可能な設計 Reusable modular design ・ヒートシンク交換可能 Interchangeable heat sink options ・メンテナンスと修理が簡単 Easy maintenance and repair 		
Mechanical Spec	Pitch:0.4mm-0.65mm Package Size:□9mm to □20mm Pin Count:1000 pin max Contact Force:14.5gf to 30.9gf Temperature:-55℃ to +150℃ Socket Dimensions:W-43.29mm L-56.46mm H-28.86mm	Pitch:0.5mm-1.00mm Package Size:□15mm to □31mm Pin Count:900-3,600 pin Contact Force:26.3gf to 34.9gf Temperature:150℃+ Mechanical Life:50,000+ Socket Dimensions:W-65.22mm L-86.81mm H-35.63mm	Min Pitch:1.0mm Package Size:□27mm to □45mm Pin Count:1,936 pin max Contact Force:34.9gf Temperature:150℃+ Mechanical Life:50,000+ Socket Dimensions:W-80.22mm L-101.81mm H-36.67mm	Pitch:1.0mm Package Size:□45mm to □60mm Pin Count:3,481 pin max Contact Force:26.3gf to 34.9gf Temperature:150℃+ Mechanical Life:50,000+ Socket Dimensions:W-95.22mm L-116.81mm H-35.82mm
Electrical Spec	Contact Resistance:<35 mΩ Current Rating:>1.0 amp Bandwidth @-1dB:10 to 15.7GHz	Contact Resistance:<35 mΩ Self Inductance: 0.88 nH to 0.95 nH Bandwidth@-1dB:15.7 to 23.2GHz	Contact Resistance:<16 mΩ Self Inductance:0.93 nH Bandwidth @-1dB:23.2 GHz	

Test & Burn-In Socket Clamshell type & Open Top type

BGA Sockets (3)

	BGA Single beam socket, Open top	BGA M-pin probe socket, Clamshell (Q series)
	基板にハンダ付けタイプ Mounting to PCB : Solder dip	基板押し当てタイプ Mounting to PCB : Compression mount
		
Features	<ul style="list-style-type: none"> ・ シンプルな構造のZIFソケット ・ 実装密度を向上させました ・ 最大ピン配列13x21 (0.8mmピッチ) ・ 低荷重の接触方式です <ul style="list-style-type: none"> ・ Simple structure ZIF socket ・ Larger arrays: Increase socket utilization ・ Max array (pins): 13x21 (0.8mm pitch) ・ Low force contact 	<ul style="list-style-type: none"> ・ シンプルな構造のZIFソケット ・ 実装密度を向上させました ・ 最大ピン配列 13x21 (0.8mmピッチ) ・ 低荷重の接触方式です ・ 熱コントロール対応タイプ <ul style="list-style-type: none"> ・ Simple structure ZIF socket ・ Larger arrays: Increase socket utilization ・ Max array (pins): 13x21 (0.8mm pitch) ・ Low force contact ・ Thermal control compatibility
Mechanical Spec	Contact:Single Beam/Stationary Mounting:Thru hole Insertion:ZIF Contact Force:15gf Temperature:-45°C to +150°C Load Cycles:10,000 (burn-in) ; 50,000 (programming)	Pitch:0.8mm-1.00mm Package Size:□20mm to □32mm Pin Count:961-1,521 pin Contact Force:14.5gf Temperature:-55°C to +150°C Socket Dimensions:W-59.45mm L-69.80mm H-27.43mm
Electrical Spec	Contact Resistance:<50mΩ Inductance:<6nH Capacitance:<2.59pF Current Rating:1.0 amp	Contact Resistance:<35 mΩ Current Rating:>0.5 amp Bandwidth @-1dB:>15.7GHz